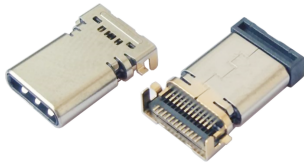


Operation: 贴片卧式 & 24PIN Type-C PLUG/沉板 1.0mm



LTEM NO.: MC-335 (3.1Type-沉板式公头)
(11.80L×8.75W×2.45H & DUL SMT LOW PCB TYPE)

C-Universal Serial Bus Connectors



Technical parameter

外焊 SMT+DIP

PROJECT	LEVEL	A[better product]	B[average product]
	Contact Rating	5A, 12V DC	
Electrical Properties	Initial Contact Resistance	30mΩ max.	50mΩ max.
	Insulation Resistance	100MΩ min.500V DC	Skey/PD: 100MΩ min.300V DC
Durable Performance	Withstand Voltage	350V AC for 1 minute	250 V AC for 1 minut
	There No Load	10,000 Cycles	8,500 Cycles
	Rated Load	8,500 Cycles	6,500 Cycles
	Storage temp.	-25℃~+75℃(Operating Temp:)	

側向導入 LATERAL

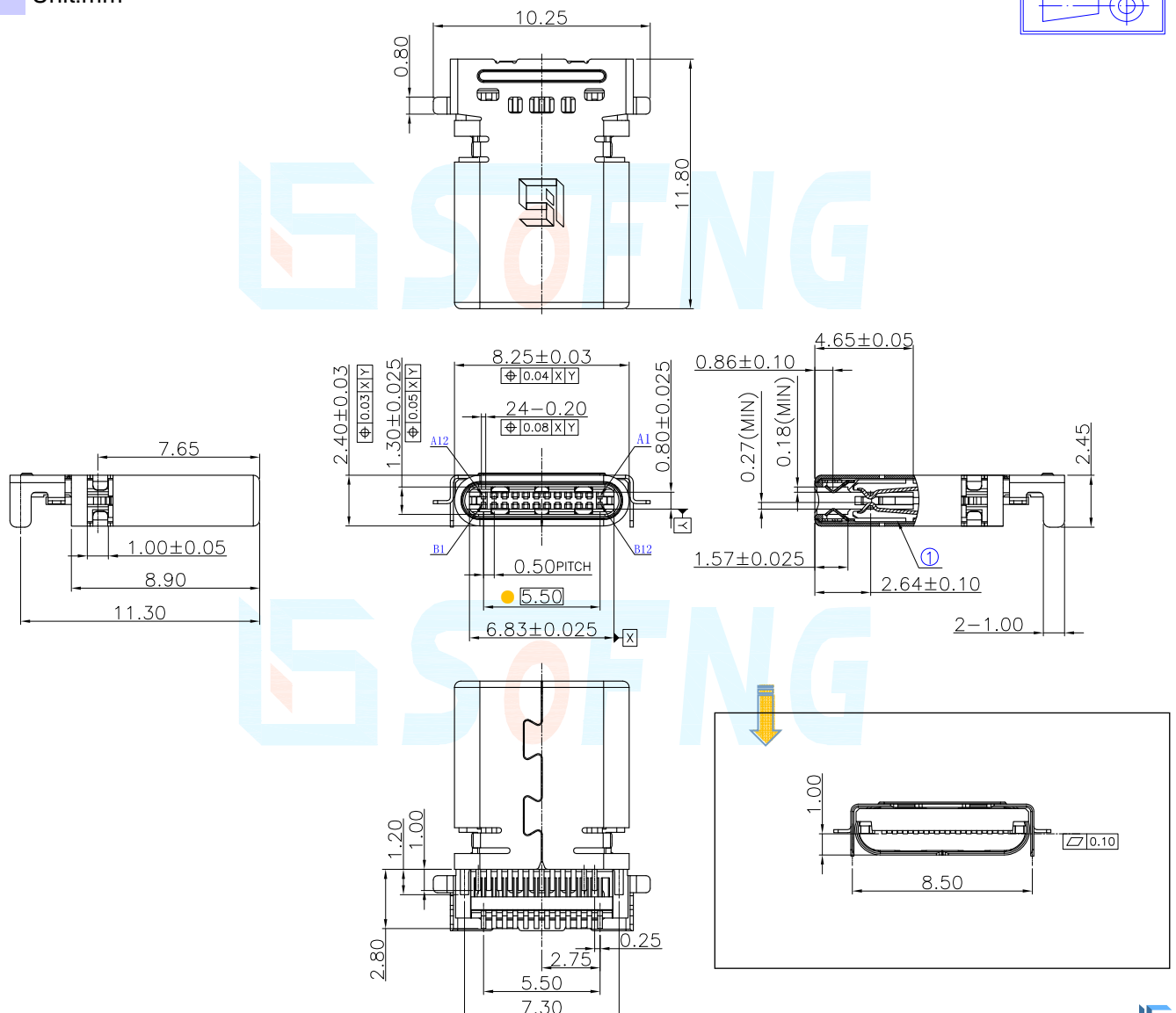
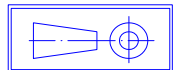
精密部品 NICETY

可靠 STABILIZE

環保材質 RoHS

Page1

Unit:mm



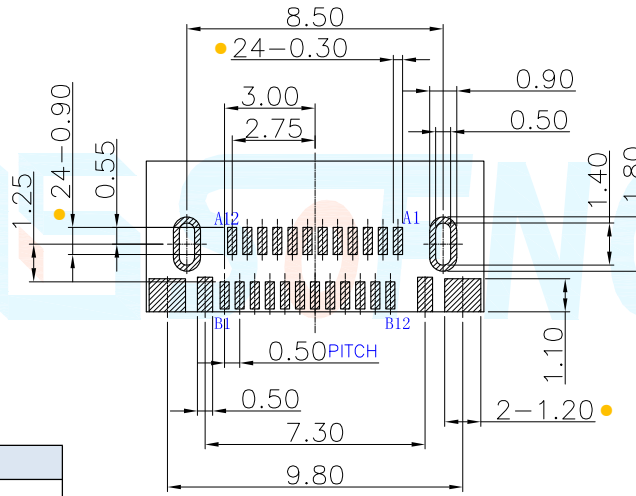
Operating Force

Inward
Exiting

5.0~8.0N. (1N.=100gram-force)
5.0~8.0N. (1N.=100gram-force)

Solder-ability (Max.)

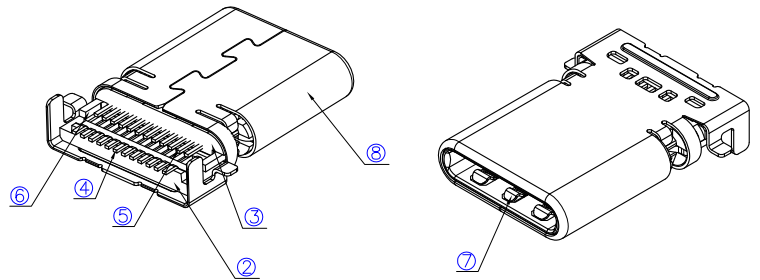
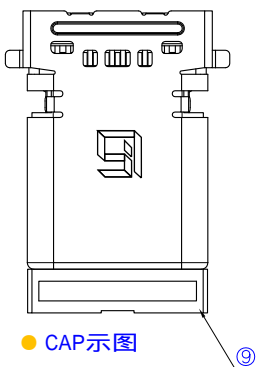
IR Reflow:255°C, 5sec. Manual :350°C, 3sec.



DECIMALS	ANGLES
X.X :±0.20	X.X :±2°
X.XX :±0.10	X.XX :±1.5°
X.XXX :±0.05	

PIN ASSIGNMENTS

PIN	Signal NAME	Description	PIN	Signal NAME	Description
A 1	GND	Ground return	B12	GND	Ground return
A 2	SSTXp1	Positive half of first SuperSpeed TX differential pair	B11	SSRXp1	Positive half of second SuperSpeed RX differential pair
A 3	SSTXn1	Negative half of first SuperSpeed TX differential pair	B10	SSRXn1	Negative half of second SuperSpeed RX differential pair
A 4	V BUS	Bus Power	B 9	V BUS	Bus Power
A 5	CC1	Configuration Channel	B 8	SBU2	Sideband Use (SBU)
A 6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B 7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A 7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B 6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A 8	SBU1	Sideband Use (SBU)	B 5	CC2	Configuration Channel
A 9	V BUS	Bus Power	B 4	V BUS	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B 3	SSTXn2	Negative half of first SuperSpeed TX differential pair2
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B 2	SSTXp2	Positive half of first SuperSpeed TX differential pair2
A12	GND	Ground return	B 1	GND	Ground return



Material declaration			
No.	NAME	MATERIAL	DESCRIPTION
① A	Housing	1	LCP(glass fiber filled)BK HIGH TEMP
② B	Insulator-A	1	LCP(glass fiber filled)BK HIGH TEMP
③ C	Insulator-B	1	LCP(glass fiber filled)BK HIGH TEMP
④ D	Terminal-A	12/F1+W10	COPPER ALLOY /Au NI Plated(t=0.15mm)
⑤ E	Terminal-B	12/F1+W10	COPPER ALLOY /Au NI Plated(t=0.15mm)
⑥ F	Latch	1	Stainless steel:t=0.3mm
⑦ G	Spring Sheet	2	COPPER ALLOY /Au NI Plated(t=0.10mm)
⑧ H	Shell	1/S1+N5	STAINLESS STEEL(t=0.15mm)
⑨ I	Cover	1	LCP(glass fiber filled)BK HIGH TEMP